

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) Method for transferring at least one element (12) from a donor substrate (10) to a target substrate (40), the element to be transferred being made integral with a handle substrate (30) through the intermediary of a layer of glue (32) whose adherence can be degraded, a degradation of the layer of glue (32) being carried out so as to free the element to be transferred (12), characterised in that it comprises the following successive steps: a) gluing of the element to be transferred (12) from the donor substrate (10) onto the handle support (30) by the intermediary of the glue layer (32), b) thinning of the donor substrate (10), c) degradation of the adherence of the glue layer (32), d) displacement of the element to be transferred (12) onto the target substrate (40), e) separation of the element to be transferred and the handle substrate.

2. (Original) Method according to claim 1, wherein a glue used is chosen from among an epoxy glue, a glue to be hardened by ultraviolet radiation, a polymer base glue, or a glue with a wax base.

3. (currently amended) Method according to claim 1, wherein degradation of the glue layer is carried out by submitting it to a chemical treatment, a heat treatment, a radiation treatment ~~and/or~~ or a plasma treatment or a combination of said treatments.

4. (Original) Method according to claim 1, implemented for transferring a layer of material (18), and comprising a step for thinning the layer of material (18), the thinning being carried out when the layer of material (18) is integral with the handle substrate (30) and before degradation of the glue layer.

5. (Original) Method according to claim 4, comprising cutting out the layer of material (18) when the layer is integral with the handle substrate.

6. (Original) Method according to claim 1, wherein a handle substrate (30) is used with access paths (34) towards a face of the handle substrate able to be put into contact with the layer of glue.

7. (Original) Method according to claim 1 for selective transfer of components wherein the stages a) and b) are carried out collectively for an assembly of components and the stages c) and d) are repeated for sub-assemblies of components.

8. (currently amended) Method according to claim 1, wherein the detachment step includes applying traction, pressure, shearing, peeling or bending forces, or any combination of these forces, ~~and/or the application of a jet of fluid and/or the insertion of a tapered object.~~

9. (New) Method according to claim 8, wherein the detachment step further includes applying a jet of fluid.

10. (New) Method according to claim 8 , wherein the detachment step further includes the insertion of a tapered object.

11. (New) Method according to claim 1 wherein said step of degradation of the adherence of the glue layer (32) is carried out before said step of displacement of the element to be transferred (12) onto the target substrate (40).

12. (New) Method according to claim 1 wherein said step of degradation of the adherence of the glue layer (32) causes a modification of the mechanical hold compatible with ulterior separation.